

November 1997 - Revised October 2003

## High-Speed CMOS Logic Dual Monostable Multivibrator with Reset

### Features

- Overriding RESET Terminates Output Pulse
- Triggering from the Leading or Trailing Edge
- Q and  $\bar{Q}$  Buffered Outputs
- Separate Resets
- Wide Range of Output-Pulse Widths
- Schmitt Trigger on B Inputs
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The 'HC221 and CD74HCT221 are dual monostable multivibrators with reset. An external resistor ( $R_X$ ) and an external capacitor ( $C_X$ ) control the timing and the accuracy for the circuit. Adjustment of  $R_X$  and  $C_X$  provides a wide range of output pulse widths from the Q and  $\bar{Q}$  terminals. Pulse triggering on the B input occurs at a particular voltage level and is not related to the rise and fall time of the trigger pulse.

Once triggered, the outputs are independent of further trigger inputs on A and B. The output pulse can be terminated by a LOW level on the Reset ( $\bar{R}$ ) pin. Trailing Edge triggering ( $\bar{A}$ ) and leading-edge-triggering (B) inputs are provided for triggering from either edge of the input pulse. On power up, the IC is reset. If either Mono is not used each input (on the unused device) must be terminated either high or low.

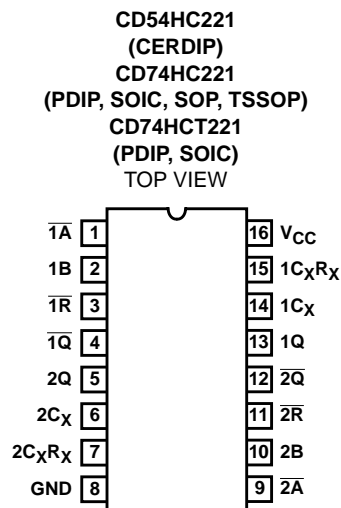
The minimum value of external resistance,  $R_X$ , is typically 500Ω. The minimum value of external capacitance,  $C_X$ , is 0pF. The calculation for the pulse width is  $t_W = 0.7 R_X C_X$  at  $V_{CC} = 4.5V$ .

### Ordering Information

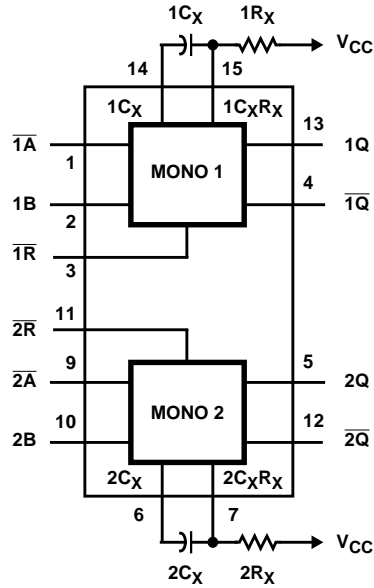
| PART NUMBER   | TEMP. RANGE (°C) | PACKAGE      |
|---------------|------------------|--------------|
| CD54HC221F3A  | -55 to 125       | 16 Ld CERDIP |
| CD74HC221E    | -55 to 125       | 16 Ld PDIP   |
| CD74HC221M    | -55 to 125       | 16 Ld SOIC   |
| CD74HC221MT   | -55 to 125       | 16 Ld SOIC   |
| CD74HC221M96  | -55 to 125       | 16 Ld SOIC   |
| CD74HC221NSR  | -55 to 125       | 16 Ld SOP    |
| CD74HC221PW   | -55 to 125       | 16 Ld TSSOP  |
| CD74HC221PWR  | -55 to 125       | 16 Ld TSSOP  |
| CD74HC221PWT  | -55 to 125       | 16 Ld TSSOP  |
| CD74HCT221E   | -55 to 125       | 16 Ld PDIP   |
| CD74HCT221M   | -55 to 125       | 16 Ld SOIC   |
| CD74HCT221MT  | -55 to 125       | 16 Ld SOIC   |
| CD74HCT221M96 | -55 to 125       | 16 Ld SOIC   |

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

### Pinout



Functional Diagram



TRUTH TABLE

| INPUTS    |   |           | OUTPUTS |           |
|-----------|---|-----------|---------|-----------|
| $\bar{A}$ | B | $\bar{R}$ | Q       | $\bar{Q}$ |
| H         | X | H         | L       | H         |
| X         | L | H         | L       | H         |
| L         | ↑ | H         |         |           |
| ↓         | H | H         |         |           |
| X         | X | L         | L       | H         |
| L         | H | ↑         |         |           |

H = High Voltage Level, L = Low Voltage Level, X = Irrelevant, ↑ = Transition from Low to High Level, ↓ = Transition from High to Low Level, = One High Level Pulse, = One Low Level Pulse

NOTE:

- For this combination the reset input must be low and the following sequence must be used: pin 1 (or 9) must be set high or pin 2 (or 10) set low; then pin 1 (or 9) must be low and pin 2 (or 10) set high. Now the reset input goes from low-to-high and the device will be triggered.

Logic Diagram



# CD54HC221, CD74HC221, CD74HCT221

## Absolute Maximum Ratings

|  |             |
|--|-------------|
| DC Supply Voltage, $V_{CC}$ .....                      | -0.5V to 7V |
| DC Input Diode Current, $I_{IK}$                       |             |
| For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....       | $\pm 20mA$  |
| DC Output Diode Current, $I_{OK}$                      |             |
| For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....       | $\pm 20mA$  |
| DC Drain Current, per Output, $I_O$                    |             |
| For $-0.5V < V_O < V_{CC} + 0.5V$ .....                | $\pm 25mA$  |
| DC Output Source or Sink Current per Output Pin, $I_O$ |             |
| For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....       | $\pm 25mA$  |
| DC $V_{CC}$ or Ground Current, $I_{CC}$ .....          | $\pm 50mA$  |

## Thermal Information

|  |                |
|--|----------------|
| Package Thermal Impedance, $\theta_{JA}$ (see Note 2): |                |
| E (PDIP) Package .....                                 | 67°C/W         |
| M (SOIC) Package .....                                 | 73°C/W         |
| NS (SOP) Package .....                                 | 64°C/W         |
| PW (TSSOP) Package .....                               | 108°C/W        |
| Maximum Junction Temperature (Plastic Package) .....   | 150°C          |
| Maximum Storage Temperature Range .....                | -65°C to 150°C |
| Maximum Lead Temperature (Soldering 10s) .....         | 300°C          |
| (SOIC - Lead Tips Only)                                |                |

## Operating Conditions

|  |                    |
|--|--------------------|
| Temperature Range, $T_A$ .....   | -55°C to 125°C     |
| Supply Voltage Range, $V_{CC}$   |                    |
| HC Types .....   | .2V to 6V          |
| HCT Types .....  | 4.5V to 5.5V       |
| DC Input or Output Voltage, $V_I, V_O$ .....                           | 0V to $V_{CC}$     |
| Input Rise and Fall Time, $t_r, t_f$ on Inputs $\bar{A}$ and $\bar{R}$ |                    |
| 2V .....   | 1000ns (Max)       |
| 4.5V .....   | 500ns (Max)        |
| 6V .....   | 400ns (Max)        |
| Input Rise and Fall Time, $t_r, t_f$ on Input B                        |                    |
| 2V .....   | Unlimited ns (Max) |
| 4.5V .....   | Unlimited ns (Max) |
| 6V .....   | Unlimited ns (Max) |

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

| PARAMETER                               | SYMBOL   | TEST CONDITIONS      |            | $V_{CC}$ (V) | 25°C |     |      | -40°C TO 85°C |      | -55°C TO 125°C |      | UNITS |
|---|----------|----------------------|------------|--------------|------|-----|------|---------------|------|----------------|------|-------|
|   |          | $V_I$ (V)            | $I_O$ (mA) |              | MIN  | TYP | MAX  | MIN           | MAX  | MIN            | MAX  |       |
| <b>HC TYPES</b>                         |          |                      |            |              |      |     |      |               |      |                |      |       |
| High Level Input Voltage                | $V_{IH}$ | -                    | -          | 2            | 1.5  | -   | -    | 1.5           | -    | 1.5            | -    | V     |
|   |          |                      |            | 4.5          | 3.15 | -   | -    | 3.15          | -    | 3.15           | -    | V     |
|   |          |                      |            | 6            | 4.2  | -   | -    | 4.2           | -    | 4.2            | -    | V     |
| Low Level Input Voltage                 | $V_{IL}$ | -                    | -          | 2            | -    | -   | 0.5  | -             | 0.5  | -              | 0.5  | V     |
|   |          |                      |            | 4.5          | -    | -   | 1.35 | -             | 1.35 | -              | 1.35 | V     |
|   |          |                      |            | 6            | -    | -   | 1.8  | -             | 1.8  | -              | 1.8  | V     |
| High Level Output Voltage<br>CMOS Loads | $V_{OH}$ | $V_{IH}$ or $V_{IL}$ | -0.02      | 2            | 1.9  | -   | -    | 1.9           | -    | 1.9            | -    | V     |
|   |          |                      | -0.02      | 4.5          | 4.4  | -   | -    | 4.4           | -    | 4.4            | -    | V     |
|   |          |                      | -0.02      | 6            | 5.9  | -   | -    | 5.9           | -    | 5.9            | -    | V     |
| High Level Output Voltage<br>TTL Loads  | $V_{OH}$ | $V_{IH}$ or $V_{IL}$ | -          | -            | -    | -   | -    | -             | -    | -              | -    | V     |
|   |          |                      | -4         | 4.5          | 3.98 | -   | -    | 3.84          | -    | 3.7            | -    | V     |
|   |          |                      | -5.2       | 6            | 5.48 | -   | -    | 5.34          | -    | 5.2            | -    | V     |
| Low Level Output Voltage<br>CMOS Loads  | $V_{OL}$ | $V_{IH}$ or $V_{IL}$ | 0.02       | 2            | -    | -   | 0.1  | -             | 0.1  | -              | 0.1  | V     |
|   |          |                      | 0.02       | 4.5          | -    | -   | 0.1  | -             | 0.1  | -              | 0.1  | V     |
|   |          |                      | 0.02       | 6            | -    | -   | 0.1  | -             | 0.1  | -              | 0.1  | V     |
| Low Level Output Voltage<br>TTL Loads   | $V_{OL}$ | $V_{IH}$ or $V_{IL}$ | -          | -            | -    | -   | -    | -             | -    | -              | -    | V     |
|   |          |                      | 4          | 4.5          | -    | -   | 0.26 | -             | 0.33 | -              | 0.4  | V     |
|   |          |                      | 5.2        | 6            | -    | -   | 0.26 | -             | 0.33 | -              | 0.4  | V     |

**CD54HC221, CD74HC221, CD74HCT221**

**DC Electrical Specifications (Continued)**

| PARAMETER  | SYMBOL                    | TEST CONDITIONS                    |                     | V <sub>CC</sub> (V) | 25°C |     |      | -40°C TO 85°C |      | -55°C TO 125°C |     | UNITS |
|--|---------------------------|------------------------------------|---------------------|---------------------|------|-----|------|---------------|------|----------------|-----|-------|
|  |                           | V <sub>I</sub> (V)                 | I <sub>O</sub> (mA) |                     | MIN  | TYP | MAX  | MIN           | MAX  | MIN            | MAX |       |
| Input Leakage Current  | I <sub>I</sub>            | V <sub>CC</sub> or GND             | -                   | 6                   | -    | -   | ±0.1 | -             | ±1   | -              | ±1  | μA    |
| Quiescent Device Current                                       | I <sub>CC</sub>           | V <sub>CC</sub> or GND             | 0                   | 6                   | -    | -   | 8    | -             | 80   | -              | 160 | μA    |
| <b>HCT TYPES</b>   |                           |                                    |                     |                     |      |     |      |               |      |                |     |       |
| High Level Input Voltage                                       | V <sub>IH</sub>           | -                                  | -                   | 4.5 to 5.5          | 2    | -   | -    | 2             | -    | 2              | -   | V     |
| Low Level Input Voltage  | V <sub>IL</sub>           | -                                  | -                   | 4.5 to 5.5          | -    | -   | 0.8  | -             | 0.8  | -              | 0.8 | V     |
| High Level Output Voltage<br>CMOS Loads                        | V <sub>OH</sub>           | V <sub>IH</sub> or V <sub>IL</sub> | -0.02               | 4.5                 | 4.4  | -   | -    | 4.4           | -    | 4.4            | -   | V     |
| High Level Output Voltage<br>TTL Loads                         |                           |                                    | -4                  | 4.5                 | 3.98 | -   | -    | 3.84          | -    | 3.7            | -   | V     |
| Low Level Output Voltage<br>CMOS Loads                         | V <sub>OL</sub>           | V <sub>IH</sub> or V <sub>IL</sub> | 0.02                | 4.5                 | -    | -   | 0.1  | -             | 0.1  | -              | 0.1 | V     |
| Low Level Output Voltage<br>TTL Loads                          |                           |                                    | 4                   | 4.5                 | -    | -   | 0.26 | -             | 0.33 | -              | 0.4 | V     |
| Input Leakage Current  | I <sub>I</sub>            | V <sub>CC</sub> and GND            | 0                   | 5.5                 | -    | -   | ±0.1 | -             | ±1   | -              | ±1  | μA    |
| Quiescent Device Current                                       | I <sub>CC</sub>           | V <sub>CC</sub> or GND             | 0                   | 5.5                 | -    | -   | 8    | -             | 80   | -              | 160 | μA    |
| Additional Quiescent Device Current Per Input Pin: 1 Unit Load | ΔI <sub>CC</sub> (Note 3) | V <sub>CC</sub> -2.1               | -                   | 4.5 to 5.5          | -    | 100 | 360  | -             | 450  | -              | 490 | μA    |

NOTE:

3. For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

**HCT Input Loading Table**

| INPUT      | UNIT LOADS |
|------------|------------|
| All Inputs | 0.3        |

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

**Prerequisite For Switching Function**

| PARAMETER              | SYMBOL          | V <sub>CC</sub> (V) | 25°C |     |     | -40°C TO 85°C |     | -55°C TO 125°C |     | UNITS |
|------------------------|-----------------|---------------------|------|-----|-----|---------------|-----|----------------|-----|-------|
|                        |                 |                     | MIN  | TYP | MAX | MIN           | MAX | MIN            | MAX |       |
| <b>HC TYPES</b>        |                 |                     |      |     |     |               |     |                |     |       |
| Input Pulse Width<br>A | t <sub>WL</sub> | 2                   | 70   | -   | -   | 90            | -   | 105            | -   | ns    |
|                        |                 | 4.5                 | 14   | -   | -   | 18            | -   | 21             | -   | ns    |
|                        |                 | 6                   | 12   | -   | -   | 15            | -   | 18             | -   | ns    |
| Input Pulse Width<br>B | t <sub>WH</sub> | 2                   | 70   | -   | -   | 90            | -   | 105            | -   | ns    |
|                        |                 | 4.5                 | 14   | -   | -   | 18            | -   | 21             | -   | ns    |
|                        |                 | 6                   | 12   | -   | -   | 15            | -   | 18             | -   | ns    |

**CD54HC221, CD74HC221, CD74HCT221**

**Prerequisite For Switching Function (Continued)**

| PARAMETER  | SYMBOL          | V <sub>CC</sub> (V) | 25°C |     |     | -40°C TO 85°C |     | -55°C TO 125°C |     | UNITS |
|--|-----------------|---------------------|------|-----|-----|---------------|-----|----------------|-----|-------|
|  |                 |                     | MIN  | TYP | MAX | MIN           | MAX | MIN            | MAX |       |
| Input Pulse Width<br>Reset   | t <sub>WL</sub> | 2                   | 70   | -   | -   | 90            | -   | 105            | -   | ns    |
|  |                 | 4.5                 | 14   | -   | -   | 18            | -   | 21             | -   | ns    |
|  |                 | 6                   | 12   | -   | -   | 15            | -   | 18             | -   | ns    |
| Recovery Time<br>R̄ to Ā or B   | t <sub>SU</sub> | 2                   | 0    | -   | -   | 0             | -   | 0              | -   | ns    |
|  |                 | 4.5                 | 0    | -   | -   | 0             | -   | 0              | -   | ns    |
|  |                 | 6                   | 0    | -   | -   | 0             | -   | 0              | -   | ns    |
| Output Pulse Width Q or Q̄<br>C <sub>X</sub> = 0.1μF R <sub>X</sub> = 10kΩ | t <sub>W</sub>  | 5                   | 630  | -   | 770 | 602           | 798 | 595            | 805 | μs    |
| Output Pulse Width Q or Q̄<br>C <sub>X</sub> = 28pF, R <sub>X</sub> = 2kΩ  | t <sub>W</sub>  | 4.5                 | -    | 140 | -   | -             | -   | -              | -   | ns    |
| C <sub>X</sub> = 1000pF, R <sub>X</sub> = 2kΩ                              | t <sub>W</sub>  | 4.5                 | -    | 1.5 | -   | -             | -   | -              | -   | μs    |
| C <sub>X</sub> = 1000pF, R <sub>X</sub> = 10kΩ                             | t <sub>W</sub>  | 4.5                 | -    | 7   | -   | -             | -   | -              | -   | μs    |

**HCT TYPES**

|  |                 |     |     |     |     |     |     |     |     |    |
|--|-----------------|-----|-----|-----|-----|-----|-----|-----|-----|----|
| Input Pulse Width<br>A   | t <sub>WL</sub> | 4.5 | 14  | -   | -   | 18  | -   | 21  | -   | ns |
| Input Pulse Width<br>B   | t <sub>WH</sub> | 4.5 | 14  | -   | -   | 18  | -   | 21  | -   | ns |
| Input Pulse Width<br>Reset   | t <sub>WL</sub> | 4.5 | 18  | -   | -   | 23  | -   | 27  | -   | ns |
| Recovery Time<br>R̄ to Ā or B   | t <sub>SU</sub> | 4.5 | 0   | -   | -   | 0   | -   | 0   | -   | ns |
| Output Pulse Width Q or Q̄<br>C <sub>X</sub> = 0.1μF R <sub>X</sub> = 10kΩ | t <sub>W</sub>  | 5   | 630 | -   | 770 | 602 | 798 | 595 | 805 | μs |
| Output Pulse Width Q or Q̄<br>C <sub>X</sub> = 28pF, R <sub>X</sub> = 2kΩ  | t <sub>W</sub>  | 4.5 | -   | 140 | -   | -   | -   | -   | -   | ns |
| C <sub>X</sub> = 1000pF, R <sub>X</sub> = 2kΩ                              | t <sub>W</sub>  | 4.5 | -   | 1.5 | -   | -   | -   | -   | -   | μs |
| C <sub>X</sub> = 1000pF, R <sub>X</sub> = 10kΩ                             | t <sub>W</sub>  | 4.5 | -   | 7   | -   | -   | -   | -   | -   | μs |

**Switching Specifications** Input t<sub>r</sub>, t<sub>f</sub> = 6ns

| PARAMETER                                     | SYMBOL           | TEST CONDITIONS       | V <sub>CC</sub> (V) | 25°C |     |     | -40°C TO 85°C |     | -55°C TO 125°C |     | UNITS |
|---|------------------|-----------------------|---------------------|------|-----|-----|---------------|-----|----------------|-----|-------|
|   |                  |                       |                     | MIN  | TYP | MAX | MIN           | MAX | MIN            | MAX |       |
| <b>HC TYPES</b>                               |                  |                       |                     |      |     |     |               |     |                |     |       |
| Propagation Delay,<br>Trigger Ā, B, R̄ to Q  | t <sub>PLH</sub> | C <sub>L</sub> = 50pF | 2                   | -    | -   | 210 | -             | 265 | -              | 315 | ns    |
|   |                  | C <sub>L</sub> = 50pF | 4.5                 | -    | -   | 42  | -             | 53  | -              | 63  | ns    |
|   |                  | C <sub>L</sub> = 50pF | 6                   | -    | -   | 36  | -             | 45  | -              | 54  | ns    |
|   |                  | C <sub>L</sub> = 15pF | 5                   | -    | 18  | -   | -             | -   | -              | -   | ns    |
| Propagation Delay,<br>Trigger Ā, B, R̄ to Q̄ | t <sub>PHL</sub> | C <sub>L</sub> = 50pF | 2                   | -    | -   | 170 | -             | 215 | -              | 255 | ns    |
|   |                  | C <sub>L</sub> = 50pF | 4.5                 | -    | -   | 34  | -             | 43  | -              | 51  | ns    |
|   |                  | C <sub>L</sub> = 50pF | 6                   | -    | -   | 29  | -             | 37  | -              | 43  | ns    |
|   |                  | C <sub>L</sub> = 15pF | 5                   | -    | 14  | -   | -             | -   | -              | -   | ns    |

**CD54HC221, CD74HC221, CD74HCT221**

**Switching Specifications** Input  $t_r$ ,  $t_f = 6\text{ns}$  (Continued)

| PARAMETER   | SYMBOL             | TEST CONDITIONS     | $V_{CC}$ (V) | 25°C |         |     | -40°C TO 85°C |     | -55°C TO 125°C |     | UNITS |
|---|--------------------|---------------------|--------------|------|---------|-----|---------------|-----|----------------|-----|-------|
|   |                    |                     |              | MIN  | TYP     | MAX | MIN           | MAX | MIN            | MAX |       |
| Propagation Delay,<br>$\bar{R}$ to Q  | $t_{PLH}$          | $C_L = 50\text{pF}$ | 2            | -    | -       | 160 | -             | 200 | -              | 240 | ns    |
|   |                    |                     | 4.5          | -    | -       | 32  | -             | 40  | -              | 48  | ns    |
|   |                    |                     | 6            | -    | -       | 27  | -             | 34  | -              | 41  | ns    |
| Propagation Delay,<br>$\bar{R}$ to $\bar{Q}$  | $t_{PHL}$          | $C_L = 50\text{pF}$ | 2            | -    | -       | 180 | -             | 225 | -              | 270 | ns    |
|   |                    |                     | 4.5          | -    | -       | 36  | -             | 45  | -              | 54  | ns    |
|   |                    |                     | 6            | -    | -       | 31  | -             | 38  | -              | 46  | ns    |
| Output Transition Time  | $t_{TLH}, t_{THL}$ | $C_L = 50\text{pF}$ | 2            | -    | -       | 75  | -             | 95  | -              | 110 | ns    |
|   |                    |                     | 4.5          | -    | -       | 15  | -             | 19  | -              | 22  | ns    |
|   |                    |                     | 6            | -    | -       | 13  | -             | 16  | -              | 19  | ns    |
| Input Capacitance   | $C_{IN}$           | -                   | -            | -    | 10      | -   | 10            | -   | 10             | pF  |       |
| Pulse Width Match Between<br>Circuits in the Same Package<br>$C_X = 1000\text{pF}$ , $R_X = 10\text{k}\Omega$ |                    | -                   | 4.5 to 5.5   | -    | $\pm 2$ | -   | -             | -   | -              | -   | %     |
| Power Dissipation Capacitance<br>(Notes 4, 5)   | CPD                | -                   | 5            | -    | 166     | -   | -             | -   | -              | -   | pF    |
| <b>HCT TYPES</b>  |                    |                     |              |      |         |     |               |     |                |     |       |
| Propagation Delay,<br>Trigger $\bar{A}$ , B, $\bar{R}$ to Q   | $t_{PLH}$          | $C_L = 50\text{pF}$ | 4.5          | -    | -       | 42  | -             | -   | -              | 63  | ns    |
|   |                    | $C_L = 15\text{pF}$ | 5            | -    | 18      | -   | -             | -   | -              | -   | ns    |
| Propagation Delay,<br>Trigger $\bar{A}$ , B, $\bar{R}$ to $\bar{Q}$   | $t_{PHL}$          | $C_L = 50\text{pF}$ | 4.5          | -    | -       | 34  | -             | 43  | -              | 51  | ns    |
|   |                    | $C_L = 15\text{pF}$ | 5            | -    | 14      | -   | -             | -   | -              | -   | ns    |
| Propagation Delay,<br>$\bar{R}$ to Q  | $t_{PLH}$          | $C_L = 50\text{pF}$ | 4.5          | -    | -       | 38  | -             | -   | -              | 57  | ns    |
| Propagation Delay,<br>$\bar{R}$ to $\bar{Q}$  | $t_{PHL}$          | $C_L = 50\text{pF}$ | 4.5          | -    | -       | 37  | -             | -   | -              | 56  | ns    |
| Output Transition Time  | $t_{TLH}, t_{THL}$ | $C_L = 50\text{pF}$ | 2            | -    | -       | 75  | -             | 95  | -              | 110 | ns    |
|   |                    |                     | 4.5          | -    | -       | 15  | -             | 19  | -              | 22  | ns    |
|   |                    |                     | 6            | -    | -       | 13  | -             | 16  | -              | 19  | ns    |
| Input Capacitance   | $C_{IN}$           | -                   | -            | -    | 10      | -   | 10            | -   | 10             | pF  |       |
| Pulse Width Match Between<br>Circuits in the Same Package<br>$C_X = 1000\text{pF}$ , $R_X = 10\text{k}\Omega$ |                    | -                   | 4.5 to 5.5   | -    | $\pm 2$ | -   | -             | -   | -              | -   | %     |
| Power Dissipation Capacitance<br>(Notes 4, 5)   | CPD                | -                   | 5            | -    | 166     | -   | -             | -   | -              | -   | pF    |

**NOTES:**

4.  $C_{PD}$  is used to determine the dynamic power consumption, per multivibrator.
5.  $P_D = (C_{PD} + C_L) V_{CC}^2 f_i + \Sigma$  where  $f_i$  = input frequency,  $f_o$  = output frequency,  $C_L$  = output load capacitance,  $V_{CC}$  = supply voltage.

**Test Circuits and Waveforms**



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

**FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH**

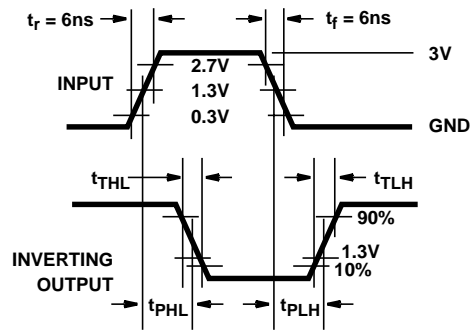


NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

**FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH**



**FIGURE 3. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**



**FIGURE 4. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**

Typical Performance Curves



FIGURE 5. HC/HCT221 OUTPUT PULSE WIDTH vs TEMPERATURE



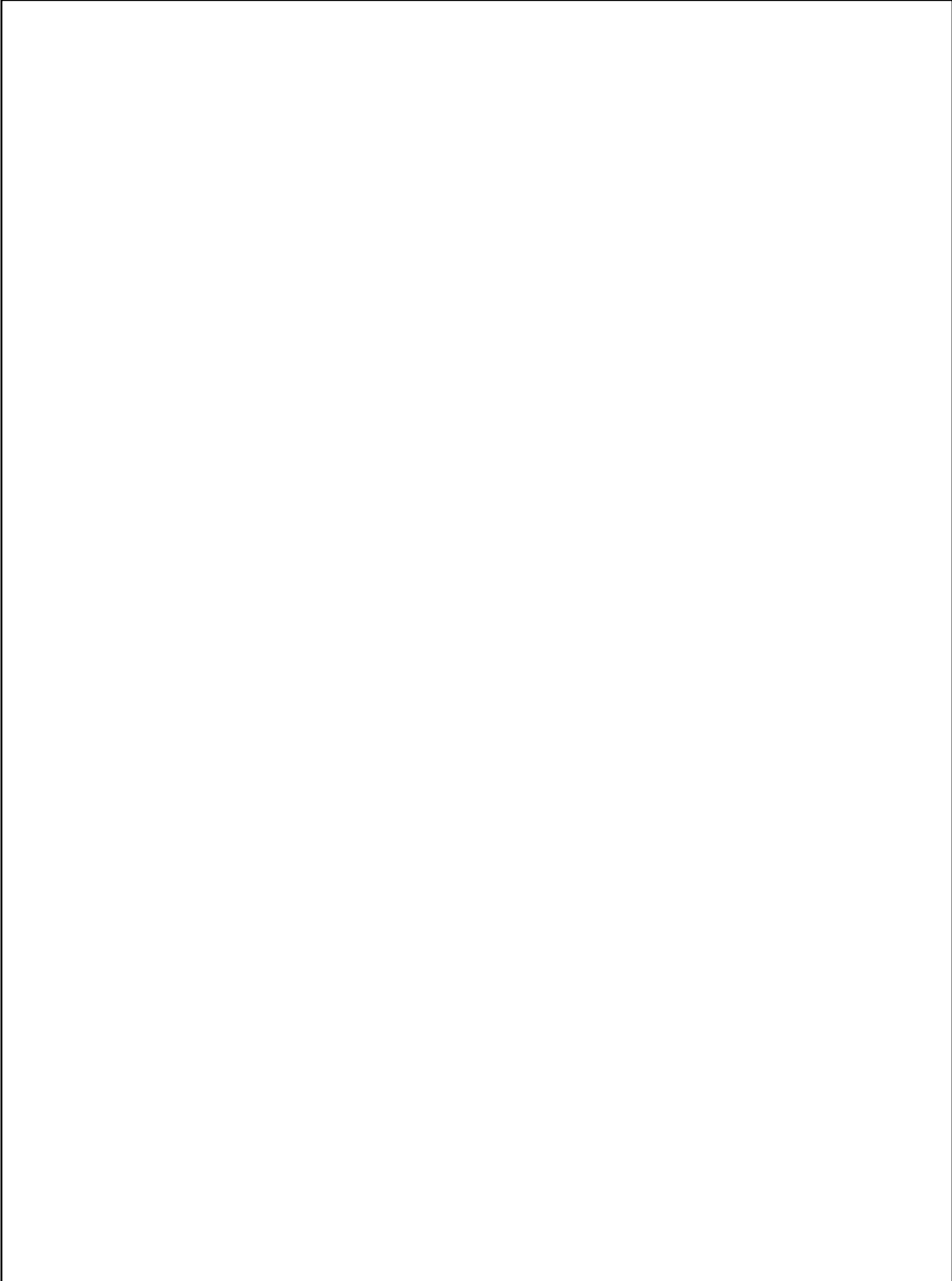
FIGURE 6. HC/HCT221 K FACTOR vs SUPPLY VOLTAGE



FIGURE 7. HC221 OUTPUT PULSE WIDTH vs  $C_X$



FIGURE 8. HC/HCT221 OUTPUT PULSE WIDTH vs  $C_X$



**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup>    | Lead/<br>Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples<br>(Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| 5962-8780501EA   | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | Call TI              | Call TI                      |                             |
| CD54HC221F       | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD54HC221F3A     | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD74HC221E       | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HC221EE4     | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HC221M       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221M96     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221M96E4   | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221M96G4   | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221ME4     | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221MG4     | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221MT      | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221MTE4    | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221MTG4    | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221NSR     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221NSRE4   | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221NSRG4   | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221PW      | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221PWE4    | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/<br>Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples<br>(Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|----------------------|------------------------------|-----------------------------|
| CD74HC221PWG4    | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221PWR     | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221PWRE4   | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221PWRG4   | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221PWT     | ACTIVE                | TSSOP        | PW              | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221PWTE4   | ACTIVE                | TSSOP        | PW              | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC221PWTG4   | ACTIVE                | TSSOP        | PW              | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT221E      | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HCT221EE4    | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HCT221M      | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT221M96    | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT221M96E4  | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT221M96G4  | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT221ME4    | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT221MG4    | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT221MT     | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT221MTE4   | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT221MTG4   | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |

<sup>(1)</sup> The marketing status values are defined as follows:

---

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF CD54HC221, CD74HC221 :**

● Catalog: [CD74HC221](#)

● Military: [CD54HC221](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


|    |   |
|----|---|
| A0 | Dimension designed to accommodate the component width     |
| B0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD74HC221M96  | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |
| CD74HC221NSR  | SO           | NS              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |
| CD74HC221PWR  | TSSOP        | PW              | 16   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| CD74HC221PWT  | TSSOP        | PW              | 16   | 250  | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| CD74HCT221M96 | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74HC221M96  | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |
| CD74HC221NSR  | SO           | NS              | 16   | 2000 | 367.0       | 367.0      | 38.0        |
| CD74HC221PWR  | TSSOP        | PW              | 16   | 2000 | 367.0       | 367.0      | 35.0        |
| CD74HC221PWT  | TSSOP        | PW              | 16   | 250  | 367.0       | 367.0      | 35.0        |
| CD74HCT221M96 | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14                     | 16                     | 18                     | 20                     |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A             | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX         | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN         | —                      | —                      | —                      | —                      |
| C MAX         | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN         | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

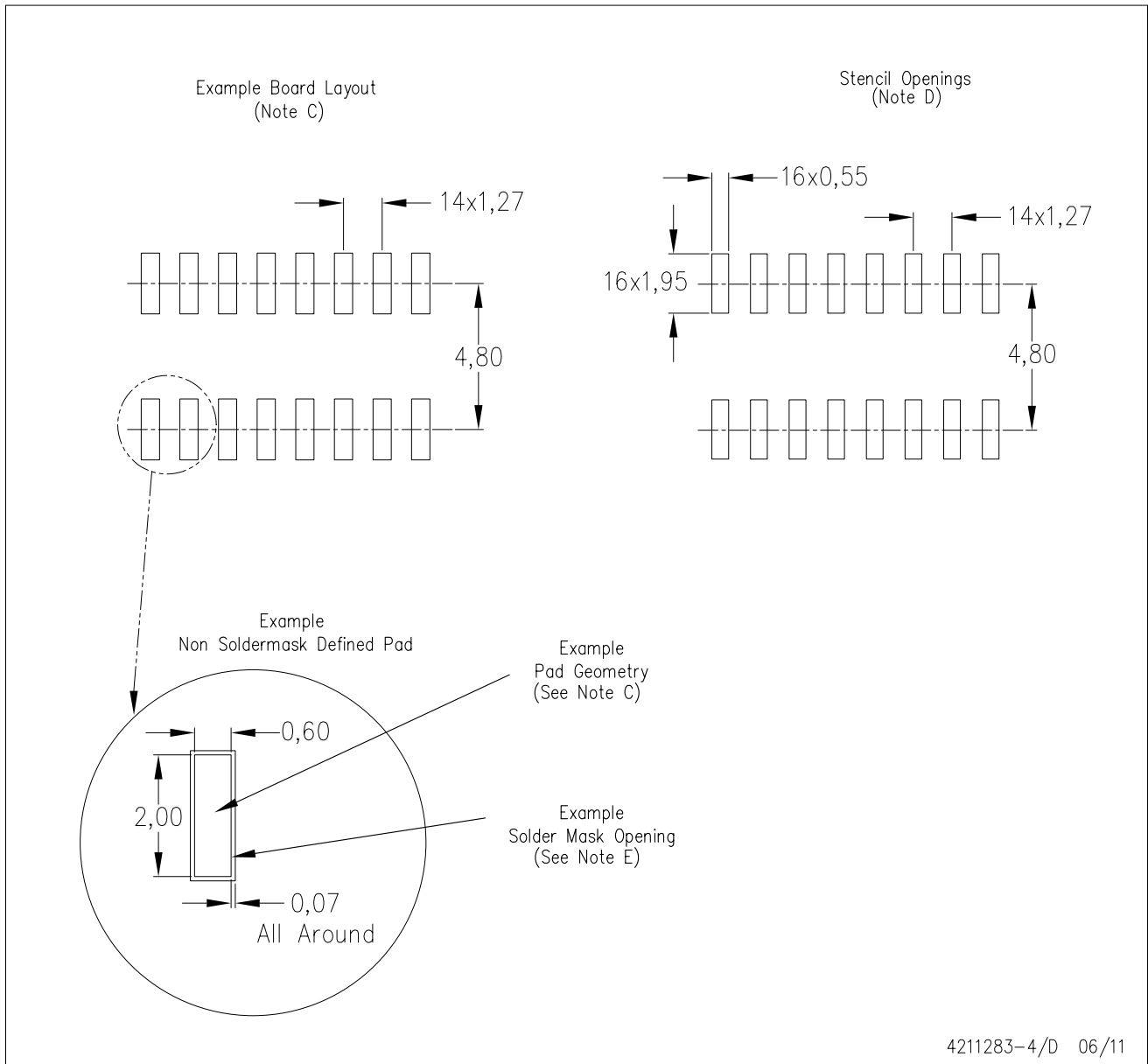
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

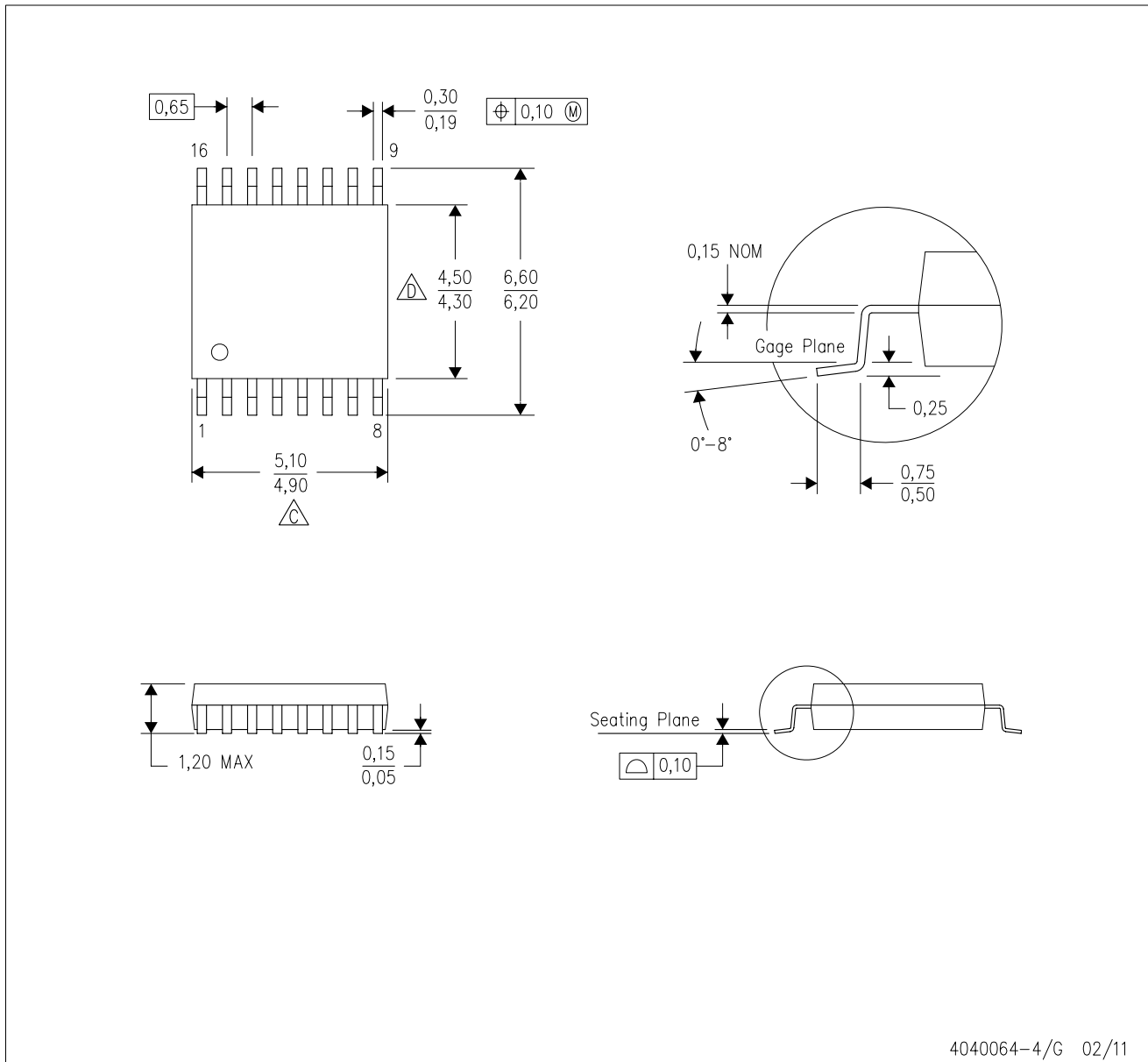
PLASTIC SMALL OUTLINE





- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

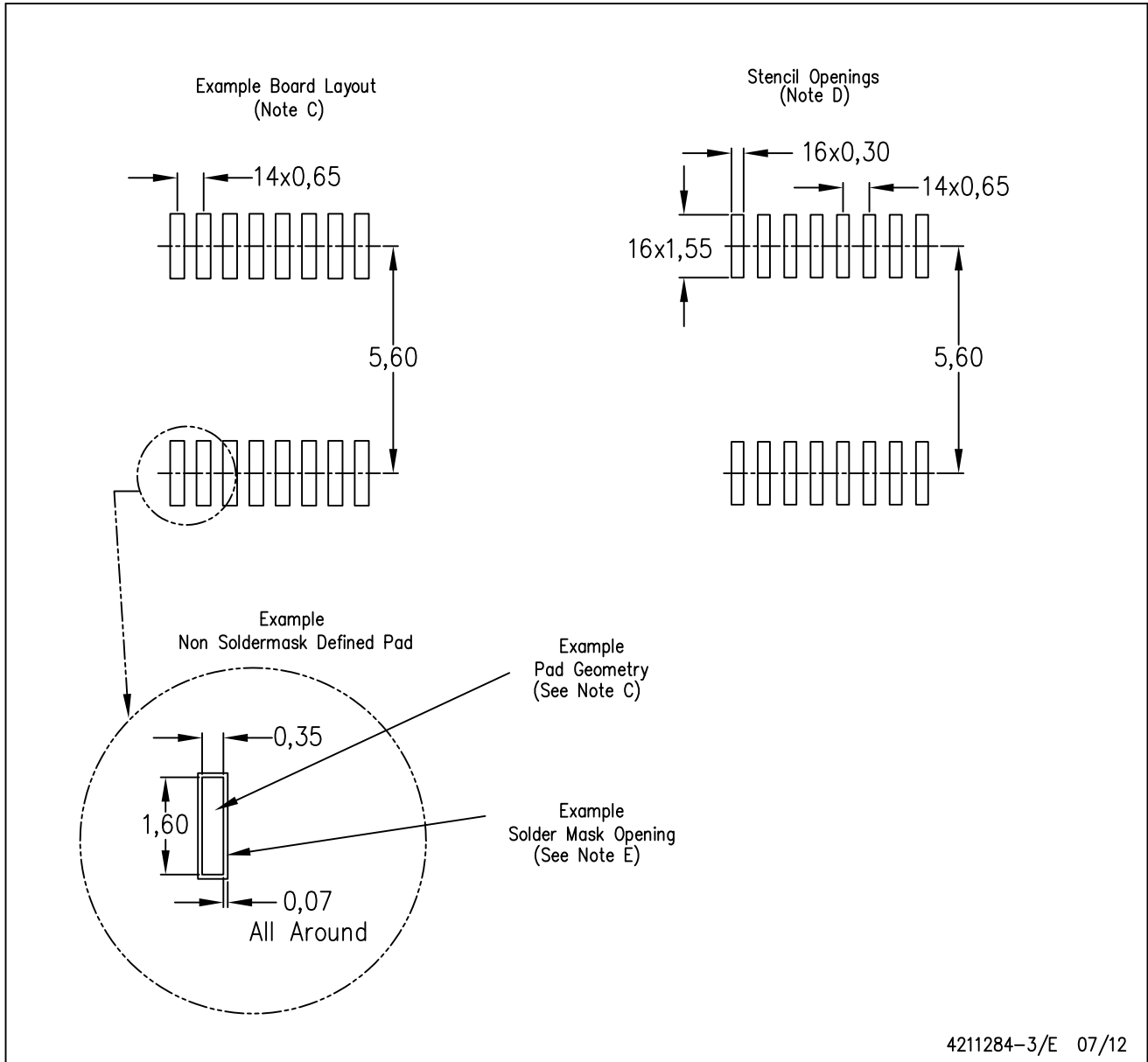


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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| OMAP Mobile Processors | <a href="http://www.ti.com/omap">www.ti.com/omap</a>                                 |
| Wireless Connectivity  | <a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a> |

### Applications

|                               |  |
|-------------------------------|--|
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| Computers and Peripherals     | <a href="http://www.ti.com/computers">www.ti.com/computers</a>                           |
| Consumer Electronics          | <a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>                   |
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